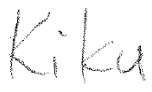


APPROVAL SHEET

Customer Name : _____
Customer P/N : _____
Frequency : 26.000000 MHz
Aker Approved P/N: TXON-026000-AKLLK400
Aker MPN : TXON-026000-AKLLK400
Rev. : 1
ISSUE DATE : Dec.2.2021

APPROVED	CHECKED	PREPARED
		
APPROVED BY CUSTOMER		

AKER TECHNOLOGY CO., LTD.

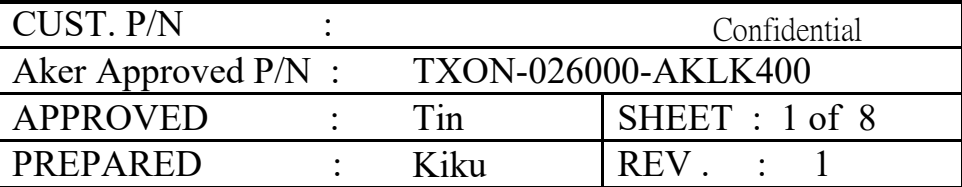
ADDRESS : NO 11-3, Jianguo Rd., Tanzi Dist., Taichung City 427, Taiwan.

TEL : 886-4-25335978 FAX : 886-4-25336011

Web: www.aker.com.tw

MSL:Level 1

RoHS compliant



SMD Temperature compensated crystal oscillator

1 . ELECTRICAL CHARACTERISTICS

■ Standard atmospheric conditions

Unless otherwise specified , the standard range of atmospheric conditions for making measurement and tests are as follow :

Ambient temperature : $25 \pm 5^{\circ}\text{C}$

Relative humidity : 40%~70%

If there is any doubt about the results , measurement shall be made within the following limits :

Ambient temperature : $25 \pm 3^{\circ}\text{C}$

Relative humidity : 40%~70%

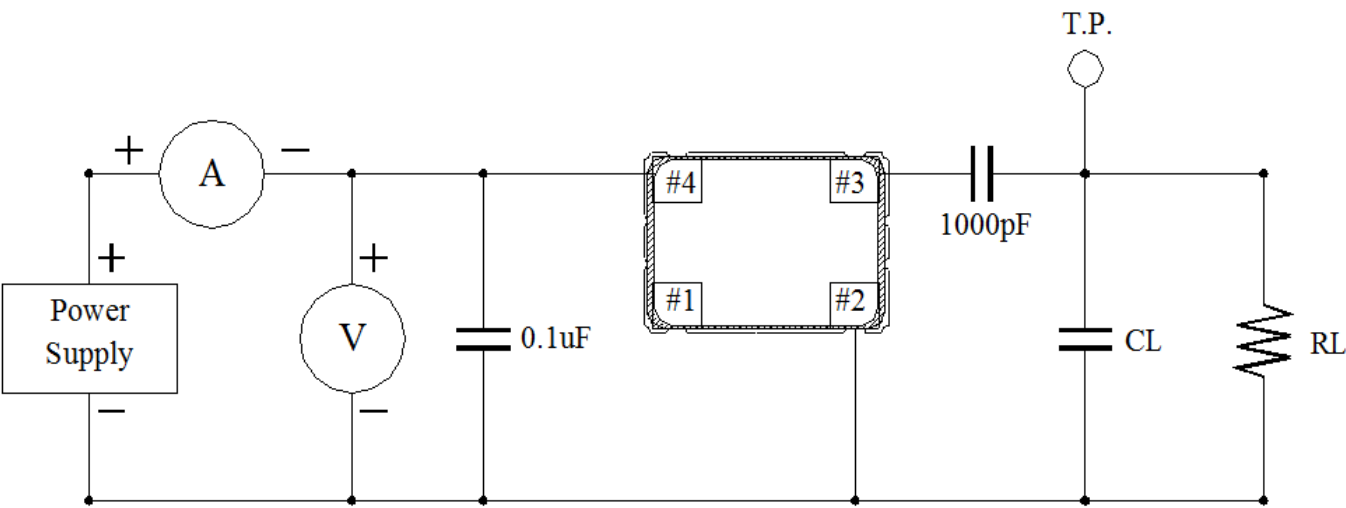
■ AKER Model : TXON-211

■ Cutting Mode : AT CUT

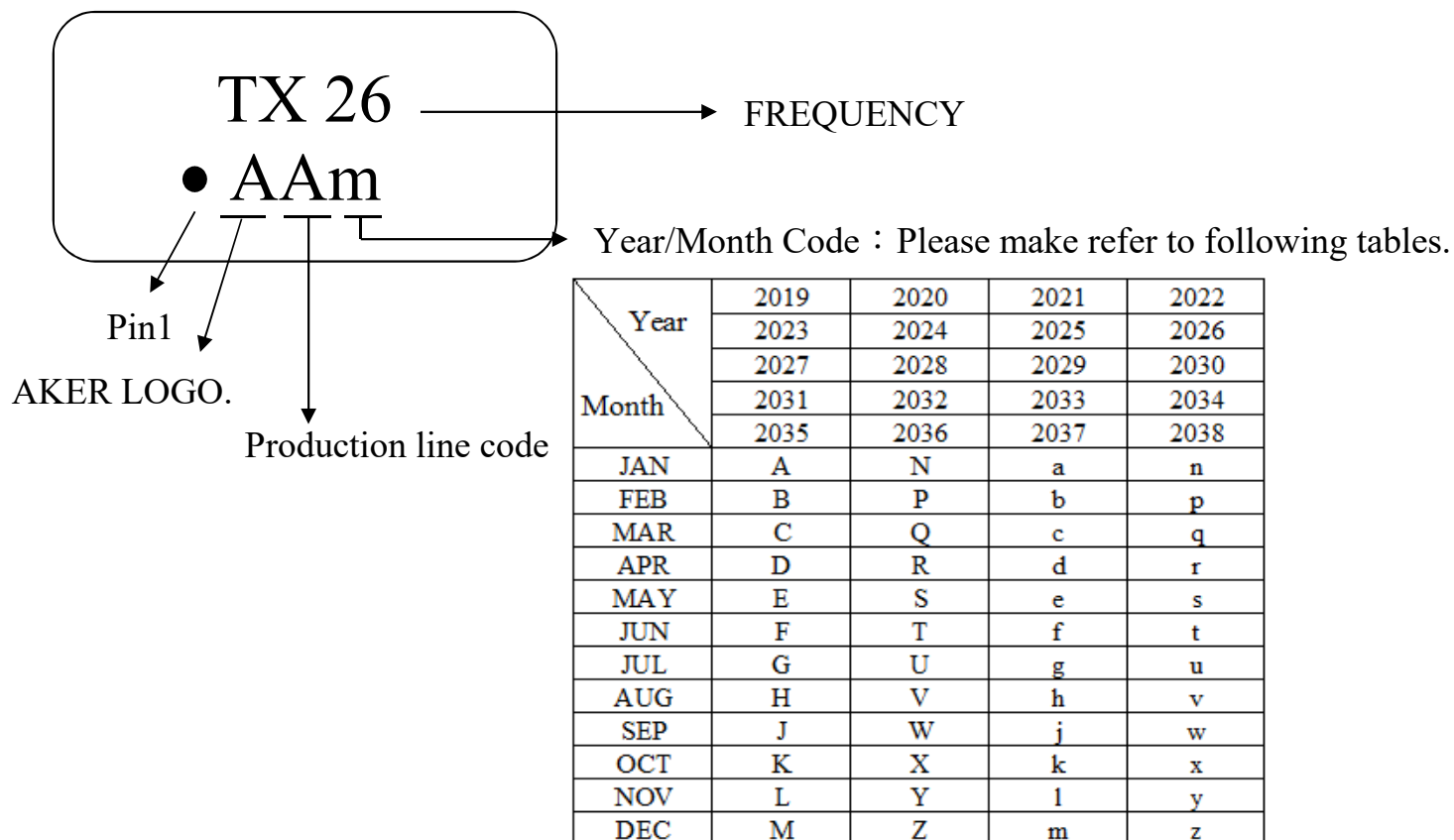
Parameters	Electrical Spec				Notes
	Min.	Typ.	Max.	Unit	
Nominal Frequency	26.000000			MHz	
Supply Voltage	3.135	3.3	3.465	V	
Frequency Tolerance	-2.0	~	2.0	ppm	After 2 times reflow soldering
Frequency Stability Over Temperature	-2.0	~	2.0	ppm	Between minimum and maximum frequency value over the specified temperature range.
Frequency Stability Over Supply Voltage	-0.2	~	0.2	ppm	
Frequency Stability Vs Load	-0.2	~	0.2	ppm	$\pm 10\%$ Change
Operating Temperature Range	-40	~	85	$^{\circ}\text{C}$	
Storage Temperature Range	-40	~	85	$^{\circ}\text{C}$	
Current Consumption			2.0	mA	
Output Waveform	Clipped Sinewave				
Output Load	10K Ω // 10pF				
Output Voltage Level	0.8			Vp-p	
Phase Noise @100Hz Offset		-114		dBc/Hz	
Phase Noise @1Khz Offset		-131		dBc/Hz	
Phase Noise @10Khz Offset		-148		dBc/Hz	
Start Up Time			2.0	mSec	
Aging	-1.0	~	1.0	ppm	First Year

Please kindly be noted that AKER DO NOT guarantee parts quality which involves human security application.

2 . TCXO TESTING CIRCUIT

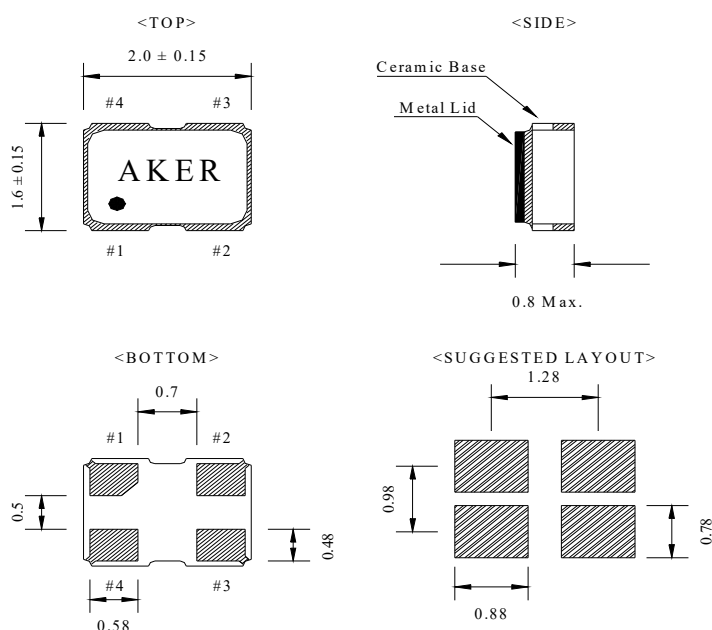


3 .MARKING :



4 . DIMENSION :

(Unit : mm)

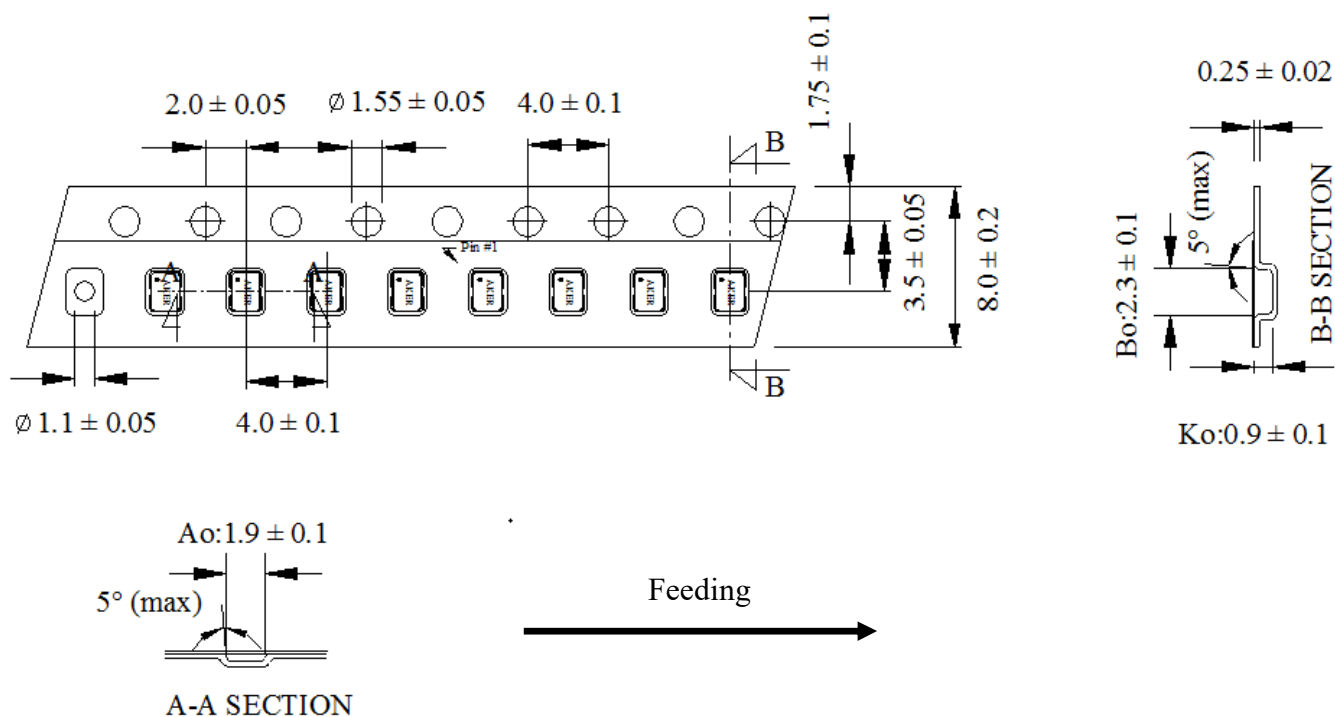


PIN No.	Connection
#1	NC / GND
#2	GND
#3	Output
#4	VDC

5. PACKING :

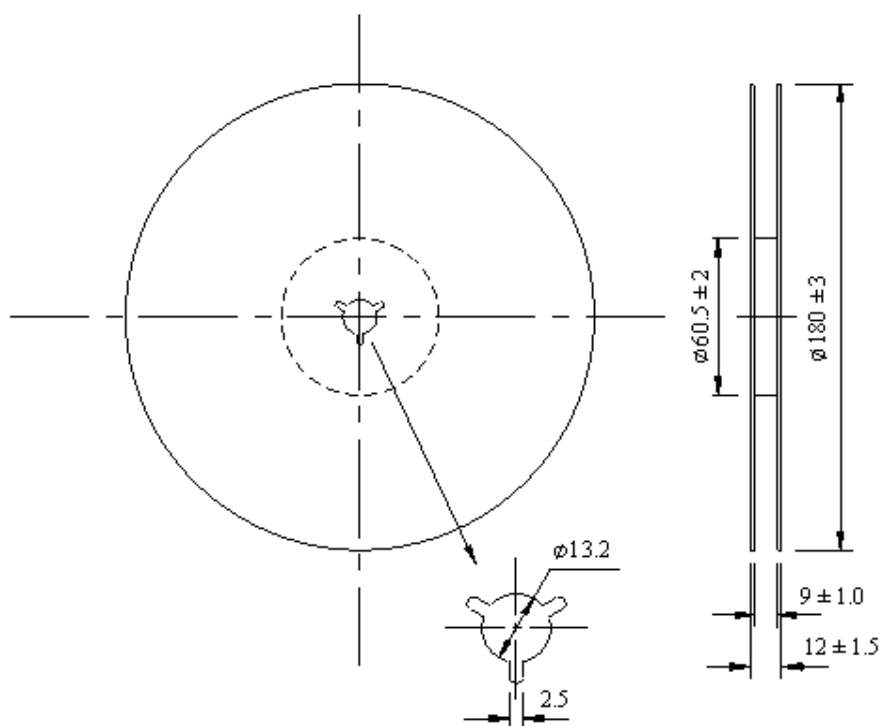
TAPE SPECIFICATION

(Unit : mm)

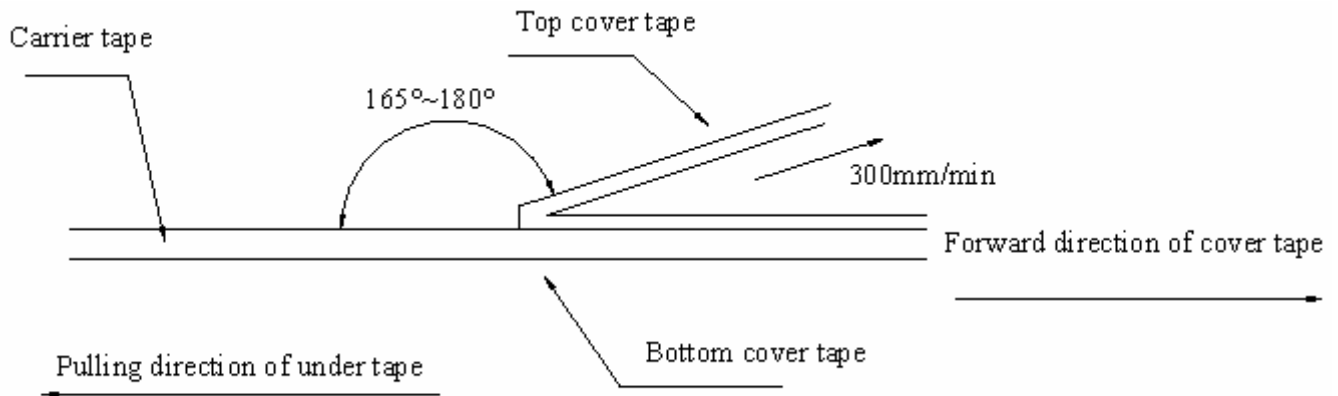


OUTLINE DIMENSION

(Unit : mm)



6. COVER TAPE ADHESION STRENGTH :

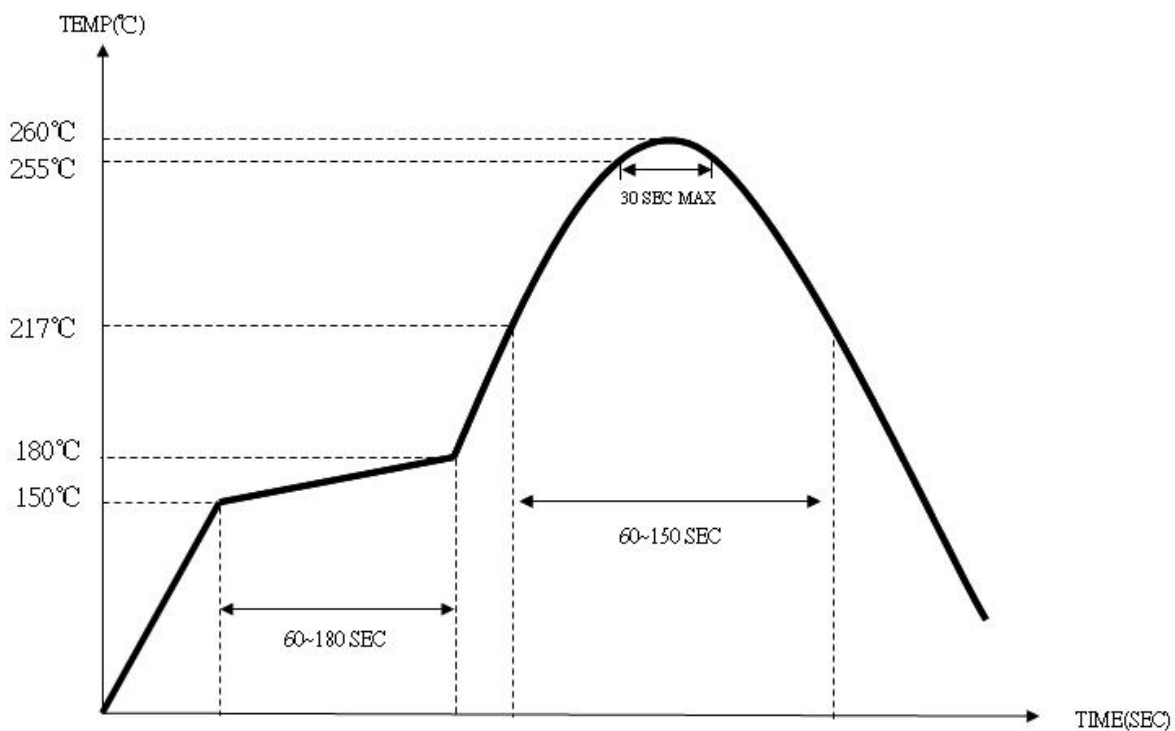


*** In the case, the cover tape is pulled off under the above conditions, the cover tape adhesion strength should be 10.2g~71.4g

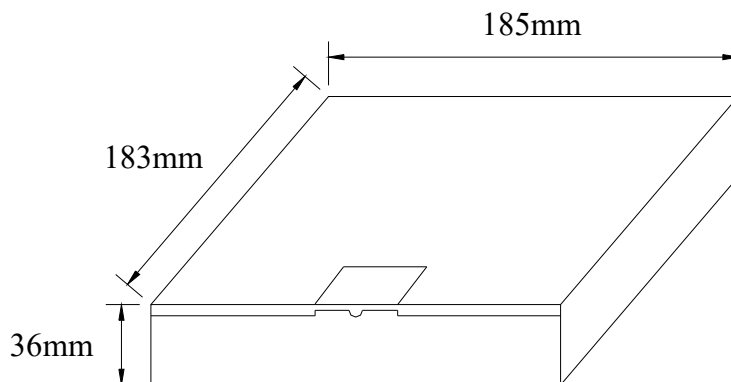
Plastic tape: 10.2g~71.4g

(Cover tape adhesion strength)

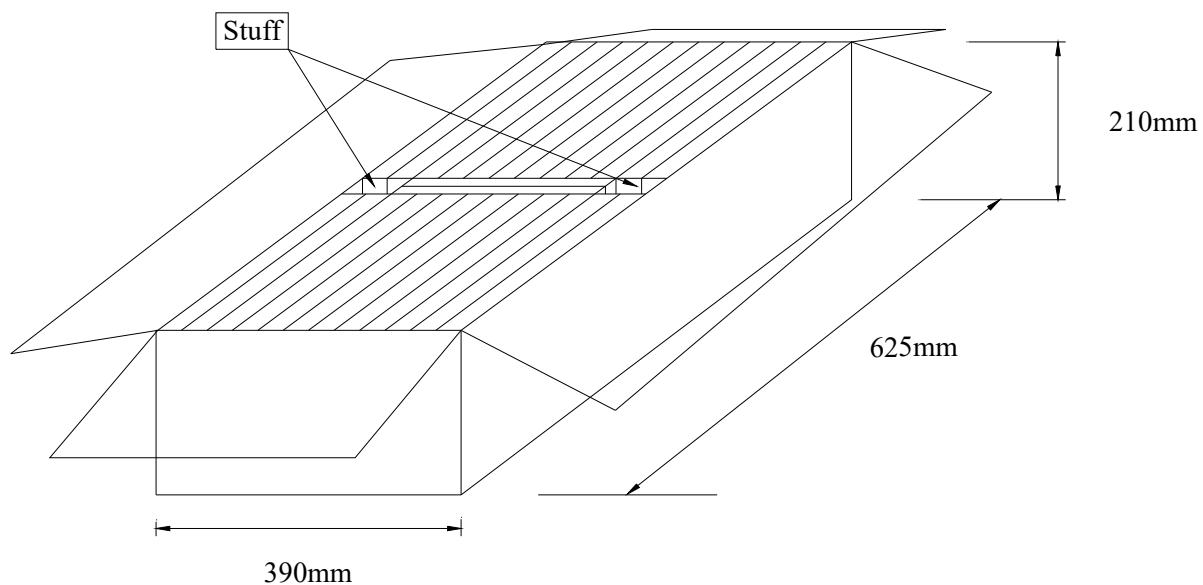
7. SOLDERING REFLOW PROFILE



8. PACKING :



PIZZA BOX = 3000 PCS / REEL(MAX)



SMD product packs 32 BOX = The outside box packs (3000 PCS * 32 BOX = 96000 PCS)(MAX)

9 .RELIABILITY SPECIFICATION

Mechanical Endurance

TEST ITEMS	TEST METHODS AND TEST CONDITION	CRITERIA
Fine Leak Test	4.5 kg/cm ² Helium bombing for 1 Hour	≤1*10 ⁻⁸ atm.cc/sec Helium
Drop Test	Free drop from 100 cm height on a hard wooden board for 3 times(board is thickness more than 30 mm)	
Vibration Test	Freq. range: 20~2000Hz Peak to peak amplitude:1.52mm Peak acceleration:20 G(196m/s ²) 3 direction(X, Y,Z) , each 20min , 4cycles	ΔF≤±2ppm
Solderability	Soldering temperature : 260±5℃ Soldering duration : 2±0.5s Solder bath	90% coated
Mechanical Shock Test	1500G, 0.5ms, 6 sides, impact each side 3 times.	ΔF≤±2ppm

Environmental Endurance

TEST ITEMS	TEST METHODS AND TEST CONDITION	CRITERIA
Temperature Cycling	-55±3℃/15±3min ~ +125±3℃/15±3min 100cycles	ΔF≤±2ppm
Low Temp. Exposure	-40±3℃ ,500±6 hrs	ΔF≤±2ppm
High Temp. & Humidity	+85℃±5℃ & 85%±5% R.H. , 168±6 hrs	ΔF≤±2ppm
Resistance To Soldering Heat Test	IR Reflow furnace with the condition 2 times Peak temp.260±3℃ , 10sec(Min.)	ΔF≤±2ppm
Aging Test	85±3℃ , 500±12hrs	ΔF≤±2ppm